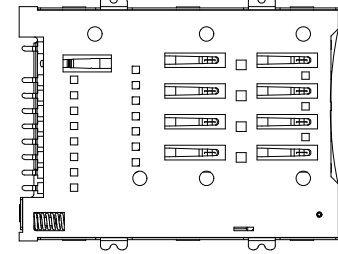
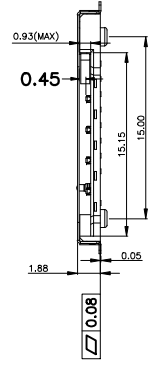
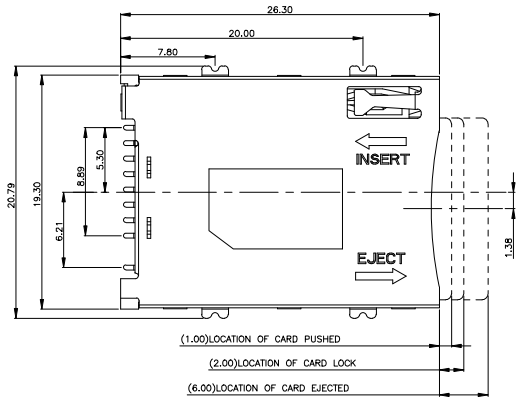
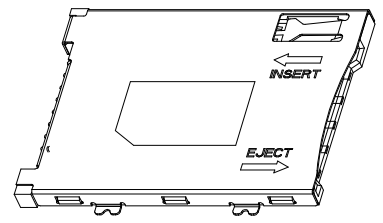
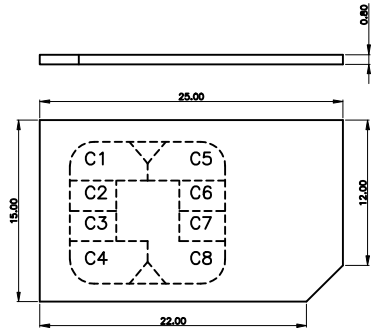
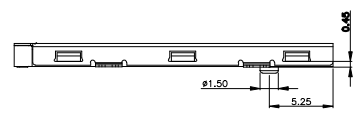
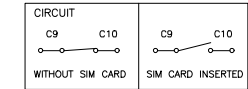




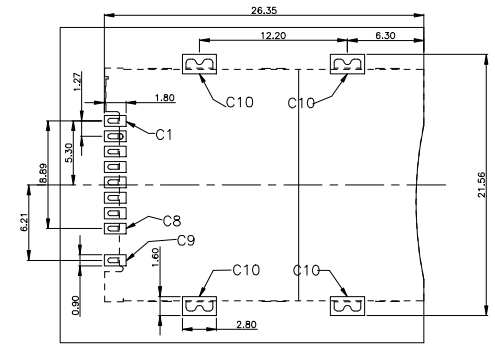
REV.	ECN NO OR DESCRIPTION	REVISED	DATE



NOTES:
 1.MATERIAL:
 HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V_0,COLOR:BLACK.
 CONTACT: COPPER ALLOYS.
 COVER: COPPER ALLOYS OR STEEL.
 2.PLATING:
 UNDERPLATE: NICKEL.
 CONTACT AREA: GOLD OVER NICKEL.
 SOLDER AREA: TIN OVER NICKEL.
 3.MULTIMEDIA CARD COMPATIBLE



Pin No.	NAME
C1	VCC OF SIM
C2	GND OF SIM
C3	RST OF SIM
C4	VPP OF SIM
C5	CLK OF SIM
C6	I/O OF SIM
C7	DATO OF SIM
C8	MCMD OF SIM
C9	CARD DETECT SWITCH
C10	GND OF SIM



RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.5	X :±2°
X.X :±0.20	X.X :±1°
X.XX :±0.10	

东莞市汉博电子科技有限公司
 DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	Mini Sim Card Push Push 8+1P Smt 磁 H1.9		
DWN	xiong	SIM-214	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:10F 1
REV: A4			
CUSTOMER COPY			